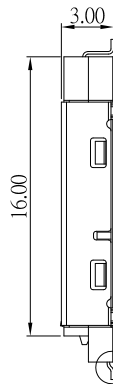
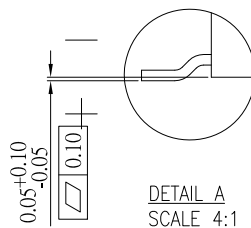
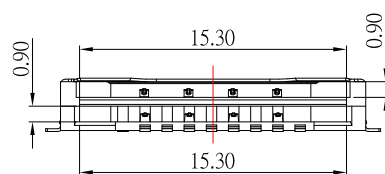
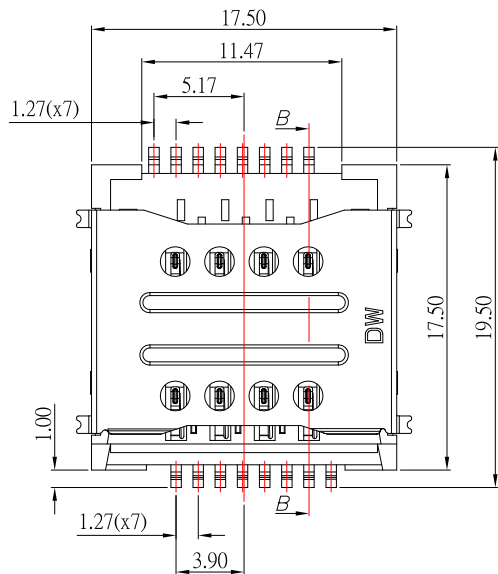
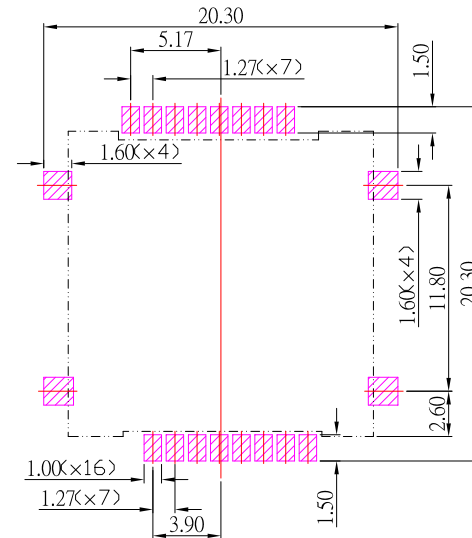
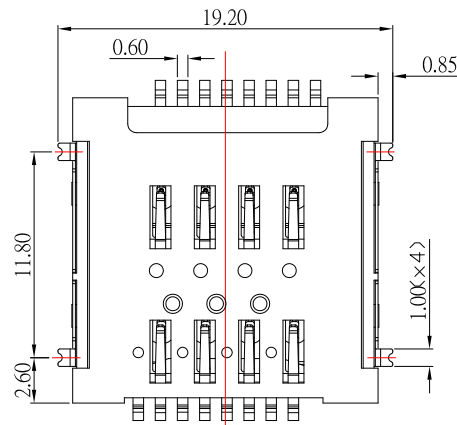


SECTION B-B



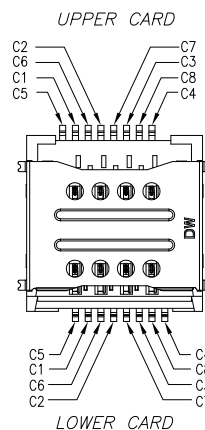
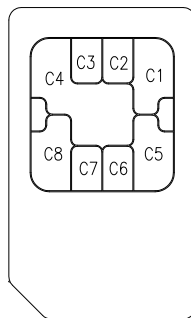
DETAIL A



P.C.B LAYOUT MOUNTING PATTERN

C1	C1:VCC
C2	C2:RST
C3	C3:CLK
C4	C4:RESERVED
C5	C5:GND
C6	C6:VPP
C7	C7:I/O
C8	C8:RESERVED

SIM CARD CIRCUIT



MATERIALS:

1. HOUSING : HIGH TEMPERATURE THERMOPLASTIC
2. CONTACT : COPPER ALLOY
3. SHELL : SUS

Finish:

1. Finish: CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
2. SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

1. INSULATION RESISTANCE : 1000MΩ MIN.
2. CONTACT RESISTANCE : 50mΩ MAX.
3. Dielectric Withstanding Voltage: 350V AC
4. Durability: 3000 cycles



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 02/27/19
DATE: 02/27/19
DATE: 02/27/19

MAT'L
FINISH
SCALE
SHEET NO.

1 : 1
1 of 1

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
雙層SIM卡座H3.0
SIM-216D202-S267
SIM-216D202-S267

SIZE
A4
VER
R